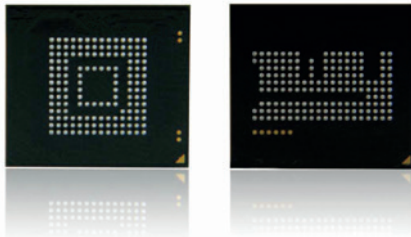


# eMMC/eMCP FROM MEMORIGHT CORPORATION



## eMCP M1870L

**Key Features:**  
 eMMC v5.1 compliant  
 Comprises eMMC and LPDDR2 DRAM  
 Excellent storage solution for mobile phones

Capacity	4+4 / 8+8
Package	BGA 162 Ball
NAND type	MLC
DRAM type	LP-DDR2
Sequential R/W (Max)	200/45 MB/s
Operation Temperature	-25°C ~ +85°C
Dimensions (mm)	11.5*13*1.0 11.5*13*1.2
VCCQ Voltage (V)	3.3V / 1.8V

## eMCP M1880L

**Key Features:**  
 eMMC v5.1 compliant  
 Comprises eMMC and LPDDR3 DRAM  
 Excellent storage solution for mobile phones

Capacity	8+8 / 16+8
Package	BGA 221 Ball
NAND type	MLC
DRAM type	LP-DDR3
Sequential R/W (Max)	270/96 MB/s
Operation Temperature	-25°C ~ +85°C
Dimensions (mm)	11.5*13*1.0 11.5*13*1.2
VCCQ Voltage (V)	3.3V / 1.8V

## eMMC M1560

**Key Features:**  
 eMMC 4.5 form factor  
 Interface: BGA 169 ball  
 MLC NAND Type  
 Wide Temperature: -25°C~+85°C

Capacity	4 / 8 GB
Package	BGA 153 Ball
NAND type	MLC
Sequential R/W (Max)	~30/15 MB/s
Operation Temperature	-25°C ~ +85°C
Dimensions (mm)	11.5*13*1.0 (Max)
VCCQ Voltage (V)	3.3V / 1.8V

## eMMC M1880

**Key Features:**  
 eMMC v5.1 compliant  
 Support CMD queue and HS400 protocol  
 Low power consumption  
 Excellent storage solution for mobile applications

Capacity	8 / 16 / 32 GB
Package	BGA 153 Ball
NAND type	MLC
Sequential R/W (Max)	270/96 MB/s
Operation Temperature	-25°C ~ +85°C
Dimensions (mm)	11.5*13*1.0 11.5*13*1.2 (Max)
VCCQ Voltage (V)	3.3V / 1.8V

## eMMC M1890

**Key Features:**  
 eMMC v5.1 compliant  
 Dedicated qualification for reliable-oriented IPC applications  
 Compact form factor is designed for IPC embedded applications

Capacity	8 / 16 / 32 GB
Package	BGA 153 Ball
NAND type	MLC
Sequential R/W (Max)	90/60 MB/s
Operation Temperature	-25°C ~ +85°C
Dimensions (mm)	11.5*13*1.0 (Max)
VCCQ Voltage (V)	3.3V